

## 70A, 60V, 0.014 Ohm, N-Channel Power MOSFETs

These are N-Channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA78440.

### Ordering Information

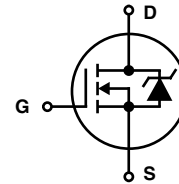
PART NUMBER	PACKAGE	BRAND
RFG70N06	TO-247	RFG70N06
RFP70N06	TO-220AB	RFP70N06
RF1S70N06	TO-262AA	F1S70N06
RF1S70N06SM	TO-263AB	F1S70N06

NOTE: When ordering use the entire part number. Add the suffix 9A to obtain the TO-263AB variant in tape and reel, e.g. RF1S70N06SM9A.

### Features

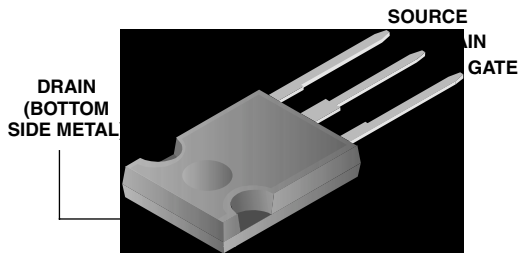
- 70A, 60V
- $r_{DS(on)} = 0.014\Omega$
- Temperature Compensated PSPICE® Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve (Single Pulse)
- 175°C Operating Temperature
- Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

### Symbol

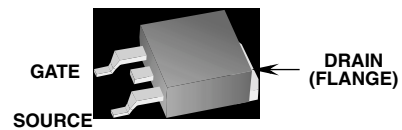


### Packaging

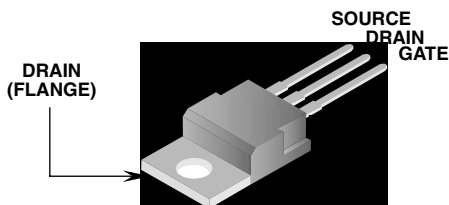
JEDEC STYLE TO-247



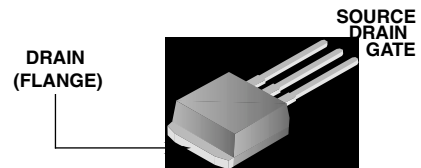
JEDEC TO-263AB



JEDEC TO-220AB



JEDEC TO-262AA



# RFG70N06, RFP70N06, RF1S70N06, RF1S70N06SM

## Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

	RFG70N06, RFP70N06 RF1S70N06, RF1S70N06SM	UNITS
Drain to Source Voltage (Note 1) . . . . .	60	V
Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1) . . . . .	60	V
Continuous Drain Current . . . . .	70	A
Pulsed Drain Current (Note 3) . . . . .	Refer to Peak Current Curve	
Gate to Source Voltage . . . . .	$\pm 20$	V
Single Pulse Avalanche Rating . . . . .	Refer to UIS Curve	A
Power Dissipation . . . . .	150	W
Linear Derating Factor . . . . .	1.0	$W/^\circ\text{C}$
Operating and Storage Temperature . . . . .	-55 to 175	$^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s. . . . .	300	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334 . . . . .	260	$^\circ\text{C}$

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

**NOTE:**

1.  $T_J = 25^\circ\text{C}$  to  $150^\circ\text{C}$ .

## Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 11)	60	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$ (Figure 10)	2	-	4	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ , $T_C = 150^\circ\text{C}$	-	-	25	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = 70\text{A}$ , $V_{GS} = 10\text{V}$ (Figure 9)	-	-	0.014	$\Omega$
Turn-On Time	$t_{(ON)}$	$V_{DD} = 30\text{V}$ , $I_D \approx 70\text{A}$ , $R_L = 0.43\Omega$ , $V_{GS} = 10\text{V}$ , $R_{GS} = 2.5\Omega$ (Figure 13)	-	-	125	ns
Turn-On Delay Time	$t_{d(ON)}$		-	12	-	ns
Rise Time	$t_r$		-	50	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	40	-	ns
Fall Time	$t_f$		-	15	-	ns
Turn-Off Time	$t_{(OFF)}$		-	-	125	ns
Total Gate Charge	$Q_g(TOT)$		$V_{GS} = 0\text{V}$ to $20\text{V}$	-	185	215
Gate Charge at 10V	$Q_g(10)$	$V_{GS} = 0\text{V}$ to $10\text{V}$	-	100	115	nC
Threshold Gate Charge	$Q_g(TH)$	$V_{GS} = 0\text{V}$ to $2\text{V}$	-	5.5	6.5	nC
Input Capacitance	$C_{ISS}$	$V_{DS} = 25\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$ (Figure 12)	-	3000	-	pF
Output Capacitance	$C_{OSS}$		-	900	-	pF
Reverse Transfer Capacitance	$C_{RSS}$		-	300	-	pF
Thermal Resistance, Junction to Case	$R_{\theta JC}$		-	-	1.0	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	TO-220 and TO-263	-	-	62	$^\circ\text{C/W}$
		TO-247	-	-	30	$^\circ\text{C/W}$

## Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 70\text{A}$		-	1.5	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 70\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$		-	125	ns

**NOTES:**

2. Pulse test: pulse width  $\leq 300\text{ms}$ , duty cycle  $\leq 2\%$ .
3. Repetitive rating: pulse width is limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3) and Peak Current Capability Curve (Figure 5).

Typical Performance Curves  $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

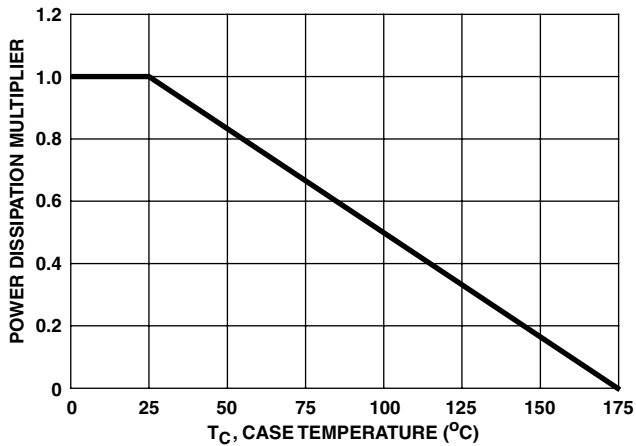


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

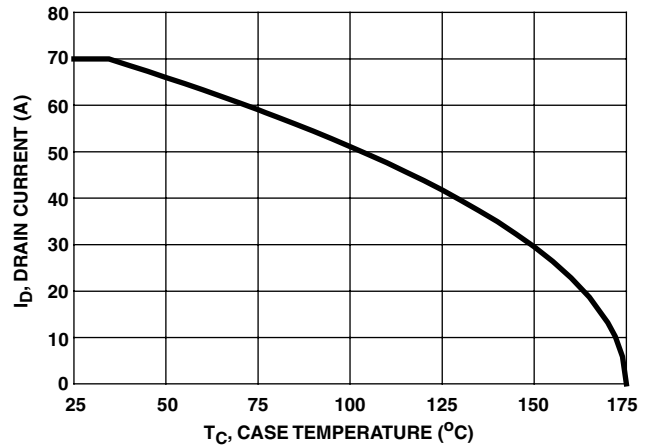


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

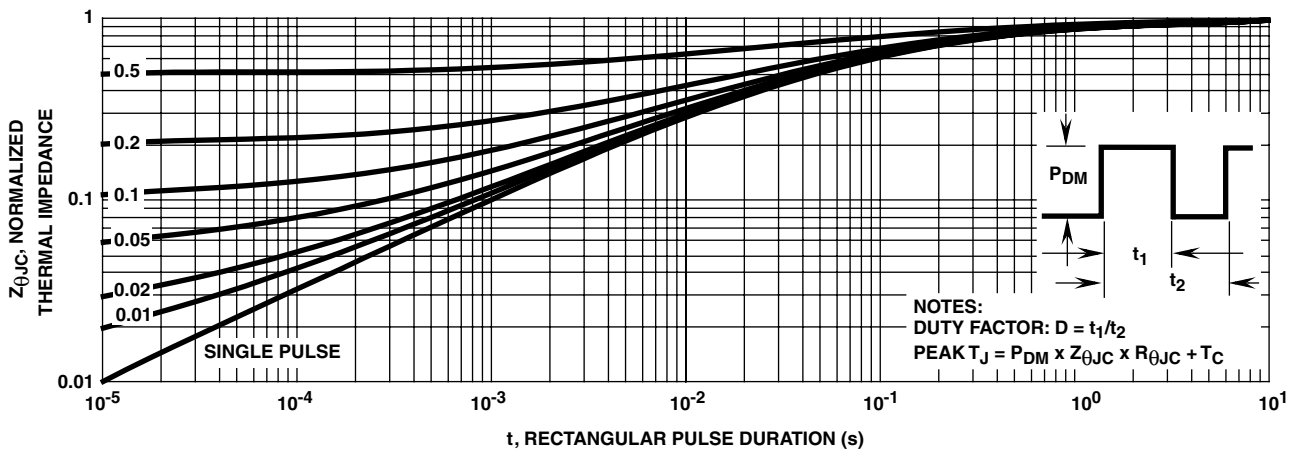


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

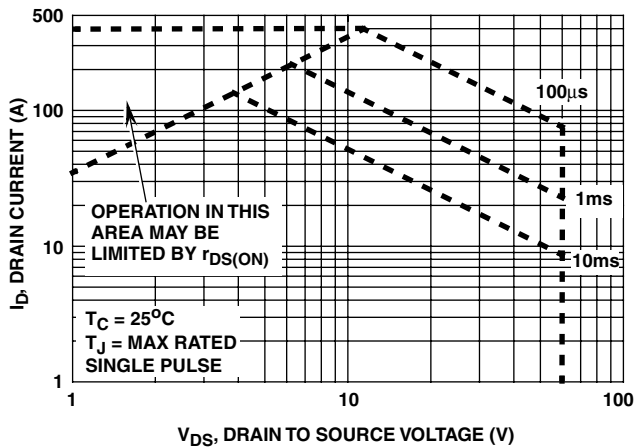


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

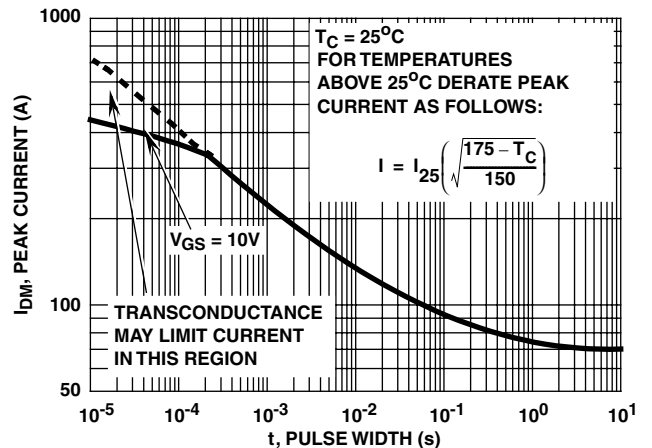
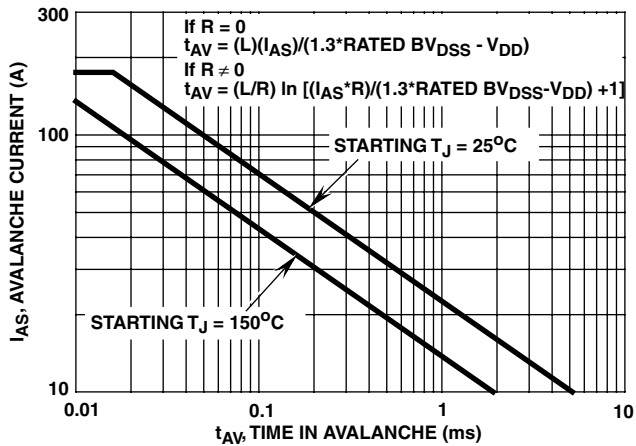
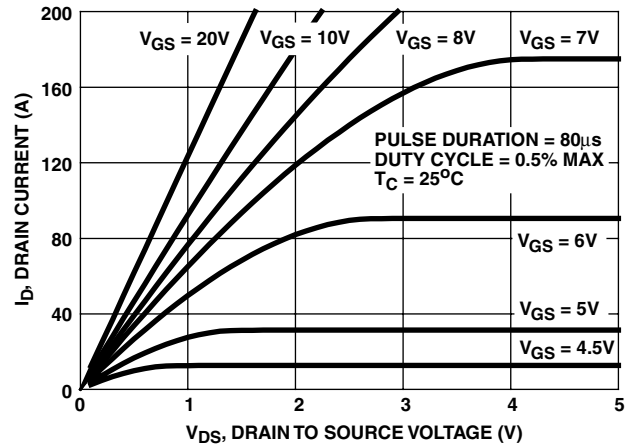


FIGURE 5. PEAK CURRENT CAPABILITY

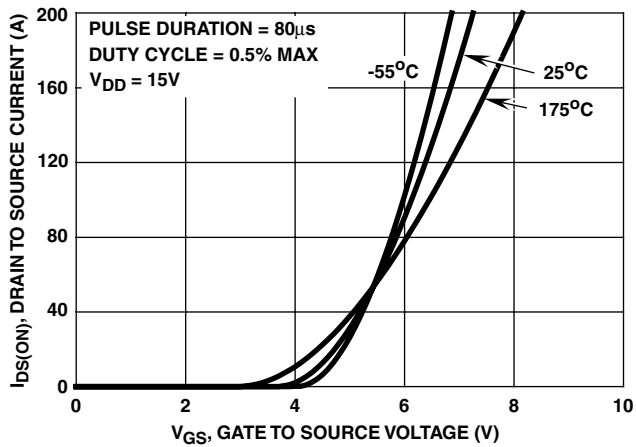
**Typical Performance Curves**  $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified (Continued)



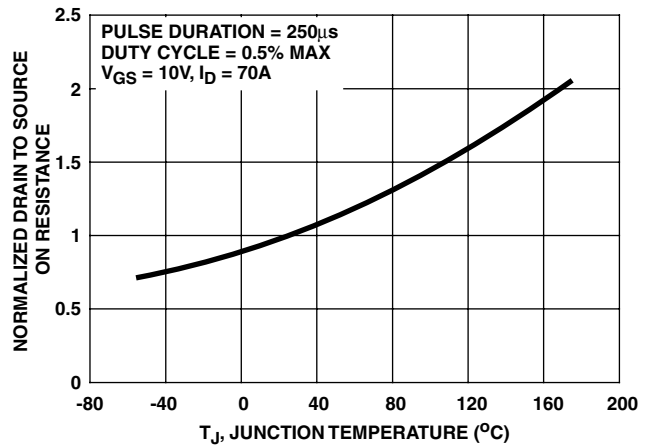
NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.  
**FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY**



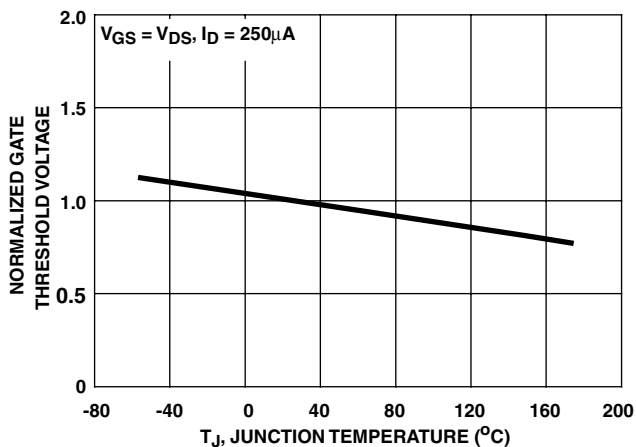
**FIGURE 7. SATURATION CHARACTERISTICS**



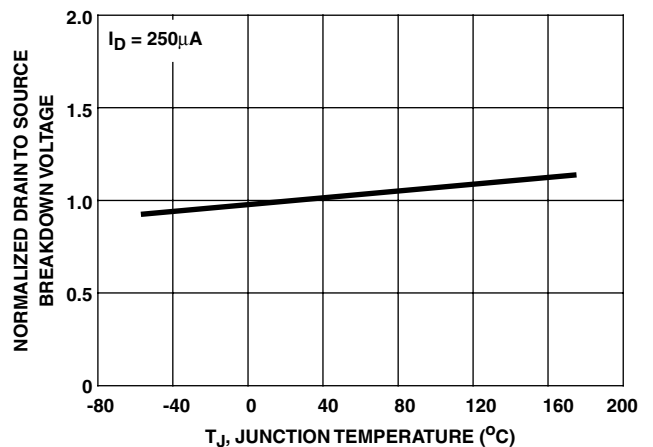
**FIGURE 8. TRANSFER CHARACTERISTICS**



**FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE**



**FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE**



**FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE**

**Typical Performance Curves**  $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified (Continued)

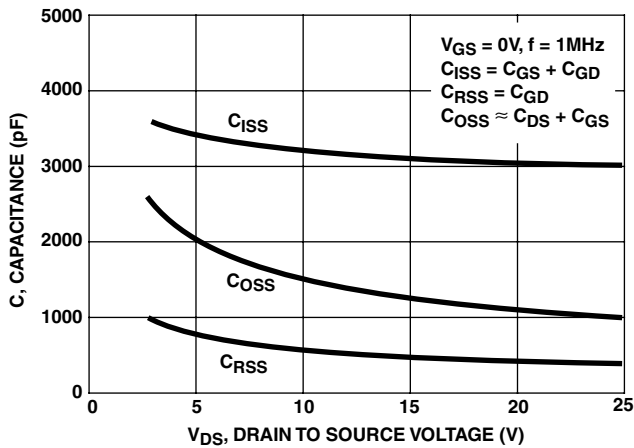
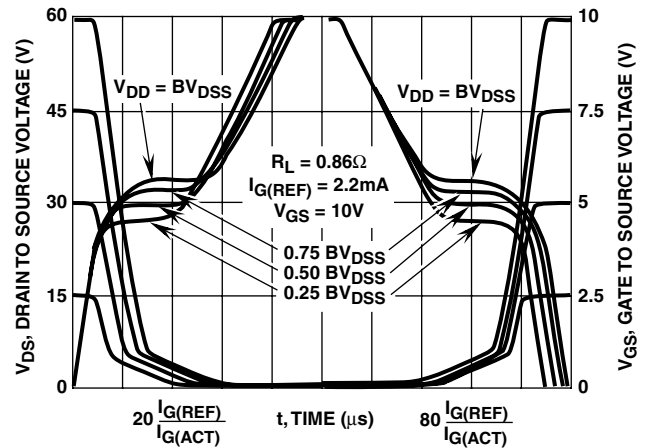


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

**Test Circuits and Waveforms**

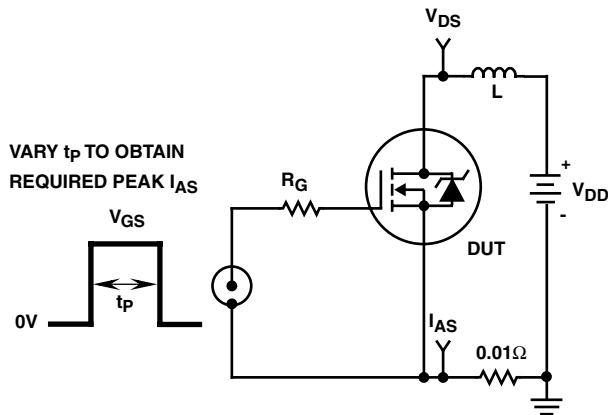


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

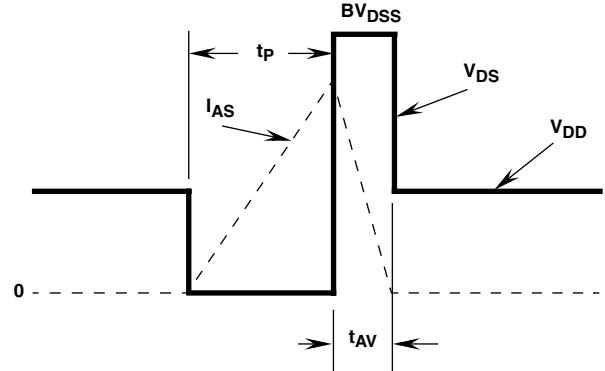


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

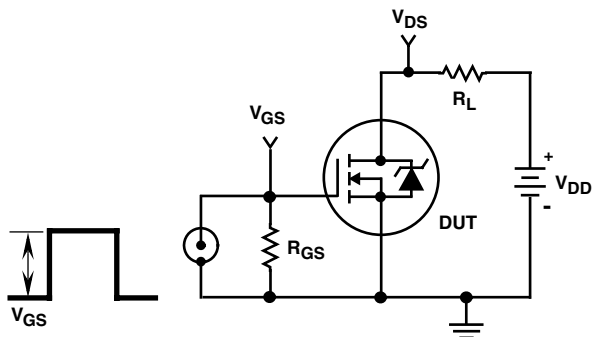


FIGURE 16. SWITCHING TIME TEST CIRCUIT

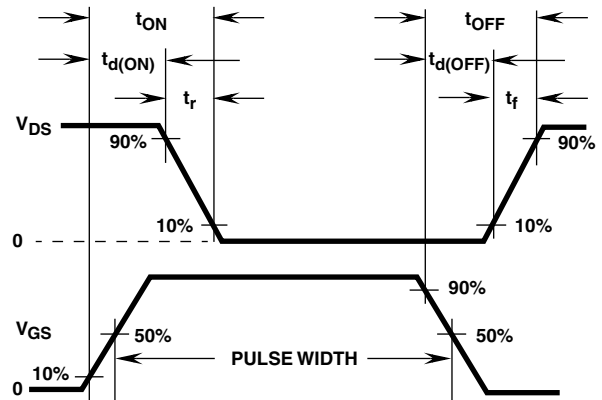


FIGURE 17. SWITCHING WAVEFORMS

Test Circuits and Waveforms (Continued)

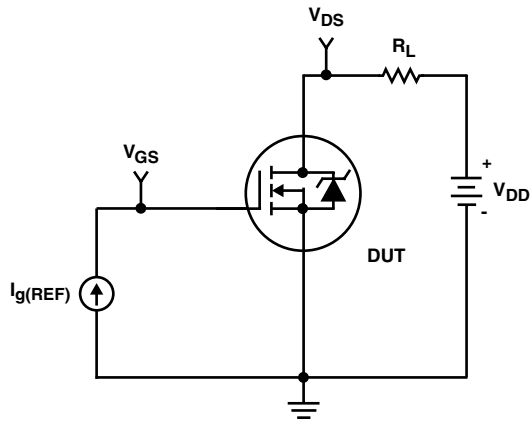


FIGURE 18. GATE CHARGE TEST CIRCUIT

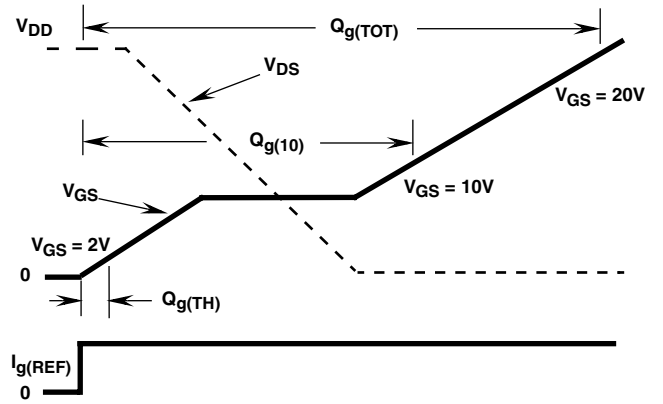


FIGURE 19. GATE CHARGE WAVEFORM



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CoolFET <sup>TM</sup>	FRFET <sup>TM</sup>	PACMAN <sup>TM</sup>	Stealth <sup>TM</sup>	
CROSSVOLT <sup>TM</sup>	GlobalOptoisolator <sup>TM</sup>	POP <sup>TM</sup>	SuperSOT <sup>TM</sup> -3	
DenseTrench <sup>TM</sup>	GTO <sup>TM</sup>	Power247 <sup>TM</sup>	SuperSOT <sup>TM</sup> -6	
DOMET <sup>TM</sup>	HiSeC <sup>TM</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>TM</sup> -8	
EcoSPARK <sup>TM</sup>	ISOPLANAR <sup>TM</sup>	QFET <sup>TM</sup>	SyncFET <sup>TM</sup>	
E <sup>2</sup> CMOS <sup>TM</sup>	LittleFET <sup>TM</sup>	QS <sup>TM</sup>	TinyLogic <sup>TM</sup>	
EnSigna <sup>TM</sup>	MicroFET <sup>TM</sup>	QT Optoelectronics <sup>TM</sup>	TruTranslation <sup>TM</sup>	
FACT <sup>TM</sup>	MicroPak <sup>TM</sup>	Quiet Series <sup>TM</sup>	UHC <sup>TM</sup>	
FACT Quiet Series <sup>TM</sup>	MICROWIRE <sup>TM</sup>	SILENT SWITCHER <sup>®</sup>	UltraFET <sup>®</sup>	

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